NEC

Solid State Relay
OCMOS FET

PS7200H-1A

4-PIN SOP, 2.2 Ω LOW ON-STATE RESISTANCE 1-ch Optical Coupled MOS FET

–NEPOC Series–

DESCRIPTION

The PS7200H-1A is a low on-state capacitance solid state relay containing a GaAs LED on the light emitting side (input side) and MOS FETs on the output side.

It is suitable for high-frequency signal control, due to its low C × R, low on-state resistance, and low off-state leakage current.

FEATURES

- Low C × R (C × R = 9.2 pF • Ω)
- Low on-state resistance (R_{on} = 2.2 Ω TYP.)
- Low output capacitance (C_{out} = 4.2 pF TYP.)
- Low off-state leakage current (I_{Loff} = 0.03 nA TYP.)
- High-speed turn-on time (t_{on} = 0.04 ms TYP.)
- 1 channel type (1 a output)
- Designed for AC/DC switching line changer
- Small and thin package (4-pin SOP, Height = 2.1 mm)
- High isolation voltage (BV = 1 500 Vr.m.s.)
- Low offset voltage
- Ordering number of taping product : PS7200H-1A-E3, E4: 900 pcs/reel
  : PS7200H-1A-F3, F4: 3 500 pcs/reel

<R> • Pb-Free product

APPLICATIONS

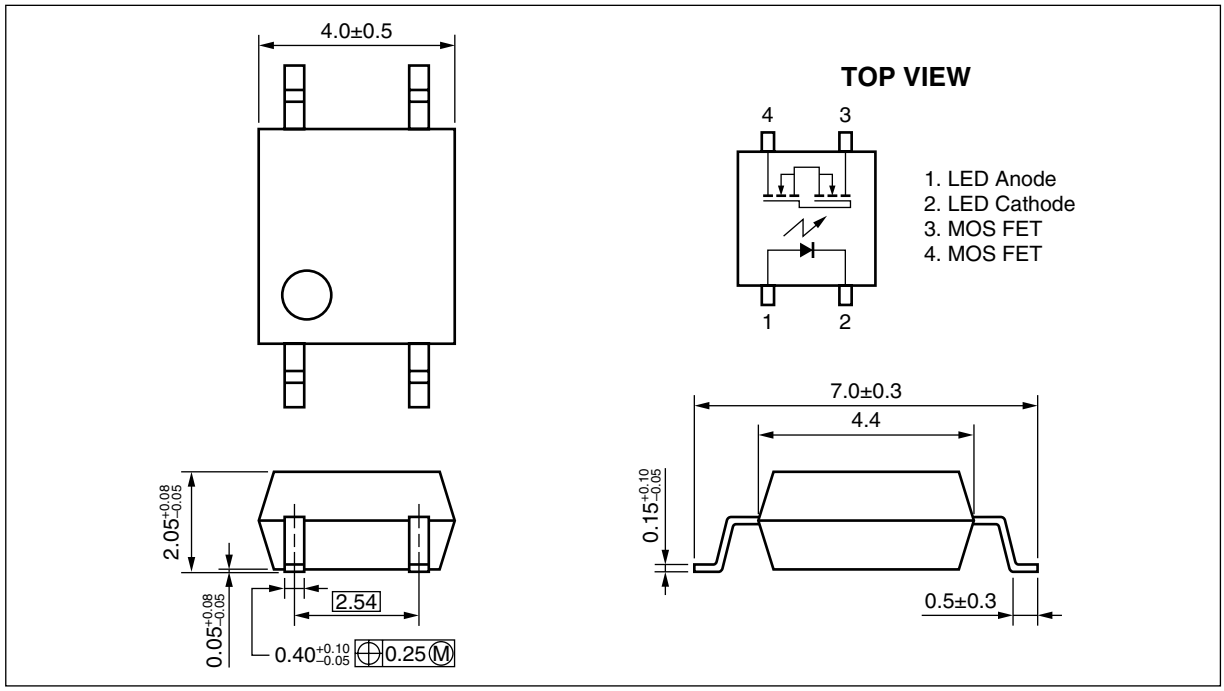
- Measurement equipment

Document No. PN10294EJ02V0DS (2nd edition)
Date Published August 2006 NS CP(K)
Printed in Japan

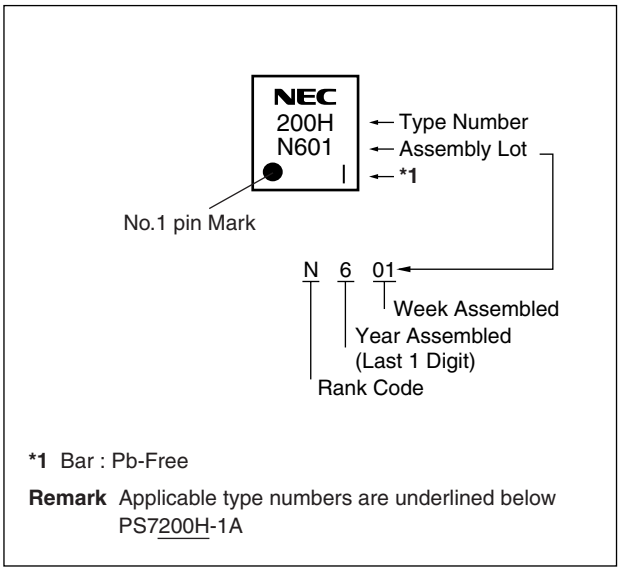
The mark <R> shows major revised points.

The revised points can be easily searched by copying an "<R>" in the PDF file and specifying it in the "Find what:" field.

PACKAGE DIMENSIONS (UNIT: mm)



<R> MARKING EXAMPLE (LASER MARKING)



1 Bar : Pb-Free

Remark Applicable type numbers are underlined below
PS7200H-1A

<R> **ORDERING INFORMATION**

Part Number	Order Number	Solder Plating Specification	Packing Style
PS7200H-1A	PS7200H-1A-A	Pb-Free	Magazine case 100 pcs
PS7200H-1A-E3	PS7200H-1A-E3-A		Embossed Tape 900 pcs/reel
PS7200H-1A-E4	PS7200H-1A-E4-A		
PS7200H-1A-F3	PS7200H-1A-F3-A		Embossed Tape 3 500 pcs/reel
PS7200H-1A-F4	PS7200H-1A-F4-A		

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current (DC)	I_F	50	mA
	Reverse Voltage	V_R	5.0	V
	Power Dissipation	P_D	50	mW
	Peak Forward Current*1	I_{FP}	1	A
MOS FET	Break Down Voltage	V_L	40	V
	Continuous Load Current	I_L	160	mA
	Pulse Load Current*2 (AC/DC Connection)	I_{LP}	320	mA
	Power Dissipation	P_D	100	mW
Isolation Voltage*3		BV	1 500	Vr.m.s.
Total Power Dissipation		P_T	150	mW
Operating Ambient Temperature		T_A	–40 to +85	°C
Storage Temperature		T_{stg}	–40 to +100	°C

***1** PW = 100 μs, Duty Cycle = 1%

***2** PW = 100 ms, 1 shot

***3** AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output
Pins 1-2 shorted together, 3-4 shorted together.

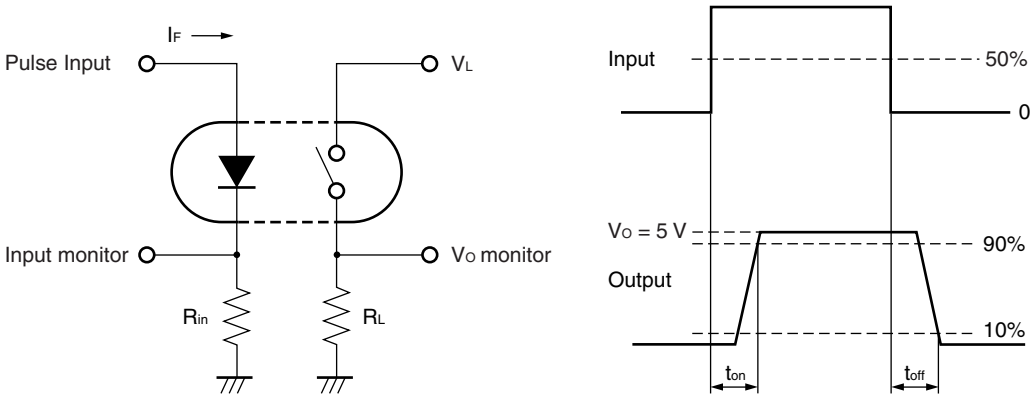
RECOMMENDED OPERATING CONDITIONS (T_A = 25°C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	I_F	2	10	20	mA
LED Off Voltage	V_F	0		0.5	V

ELECTRICAL CHARACTERISTICS (T_A = 25°C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V_F	I_F = 10 mA		1.2	1.4	V
	Reverse Current	I_R	V_R = 5 V			5.0	μA
MOS FET	Off-state Leakage Current	I_{Loff}	V_D = 40 V		0.03	10	nA
	Output Capacitance	C_{out}	V_D = 0 V, f = 1 MHz		4.2		pF
Coupled	LED On-state Current	I_{Fon}	I_L = 160 mA			2.0	mA
	On-state Resistance	R_{on1}	I_F = 10 mA, I_L = 50 mA		2.2	3.5	Ω
		R_{on2}	I_F = 10 mA, I_L = 160 mA, t ≤ 10 ms		2.2	3.5	
	Turn-on Time*1, 2	t_{on}	I_F = 10 mA, V_O = 5 V, R_L = 500 Ω,		0.04	0.5	ms
	Turn-off Time*1, 2	t_{off}	PW ≥ 10 ms		0.25	1.0	
	Isolation Resistance	R_{I-O}	V_{I-O} = 1.0 kV_{DC}	10^9			Ω
	Isolation Capacitance	C_{I-O}	V = 0 V, f = 1 MHz		0.4		pF

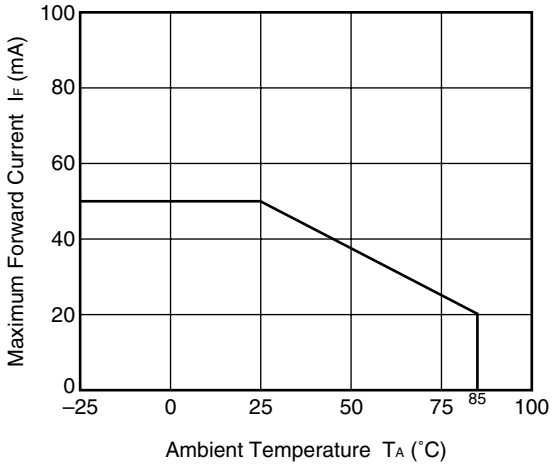
***1** Test Circuit for Switching Time



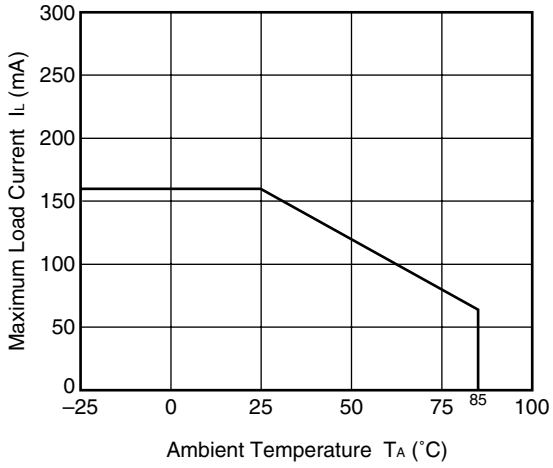
***2** The turn-on time and turn-off time are specified as input-pulse width ≥ 10 ms.
Be aware that when the device operates with an input-pulse width less than 10 ms, the turn-on time and turn-off time will increase.

TYPICAL CHARACTERISTICS (T_A = 25°C, unless otherwise specified)

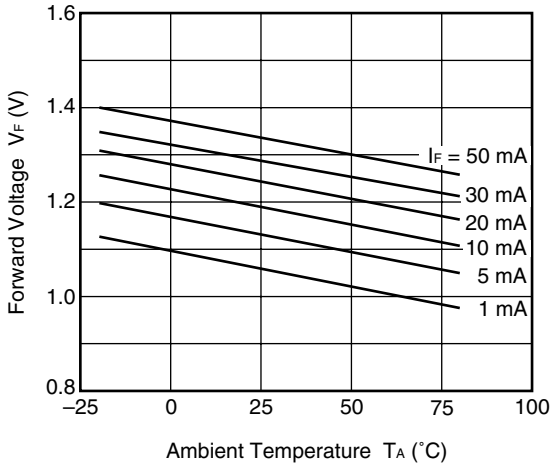
MAXIMUM FORWARD CURRENT vs. AMBIENT TEMPERATURE



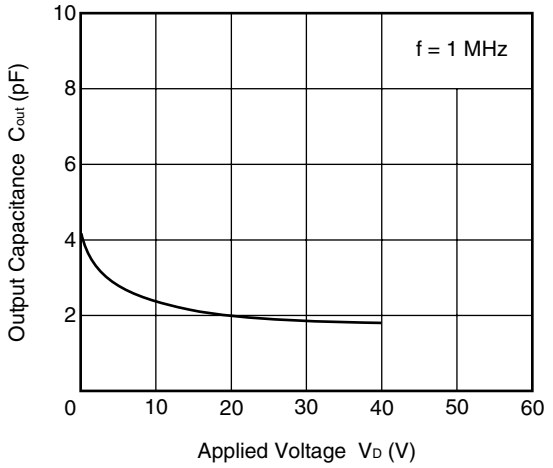
MAXIMUM LOAD CURRENT vs. AMBIENT TEMPERATURE



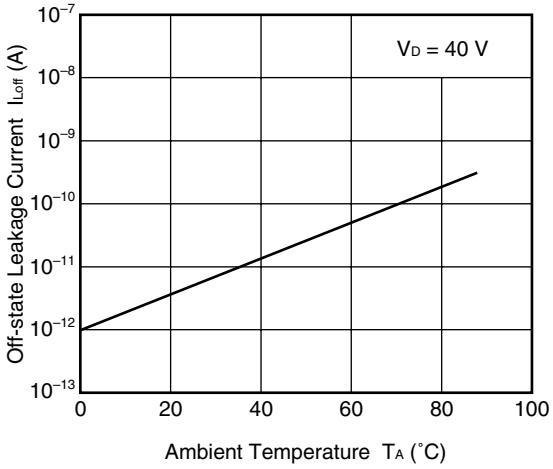
FORWARD VOLTAGE vs. AMBIENT TEMPERATURE



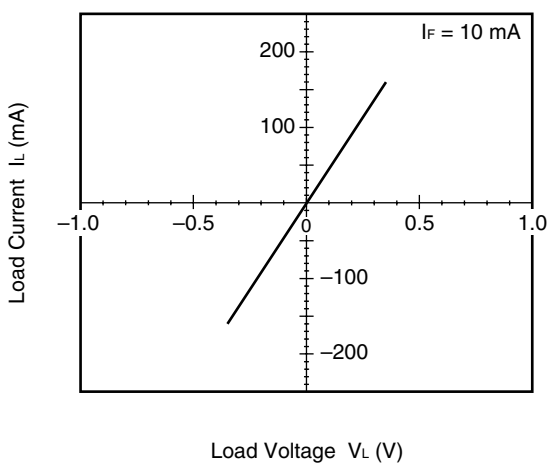
OUTPUT CAPACITANCE vs. APPLIED VOLTAGE



OFF-STATE LEAKAGE CURRENT vs. AMBIENT TEMPERATURE

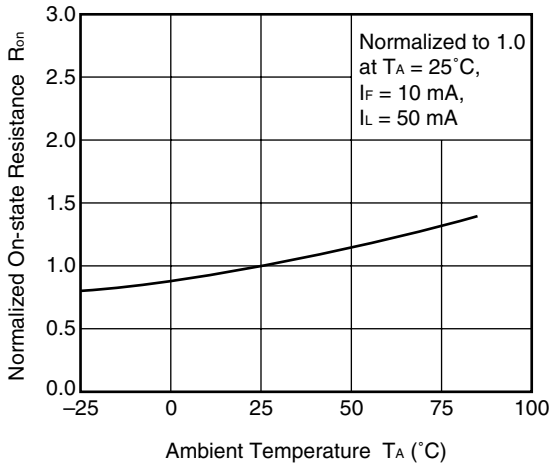


LOAD CURRENT vs. LOAD VOLTAGE

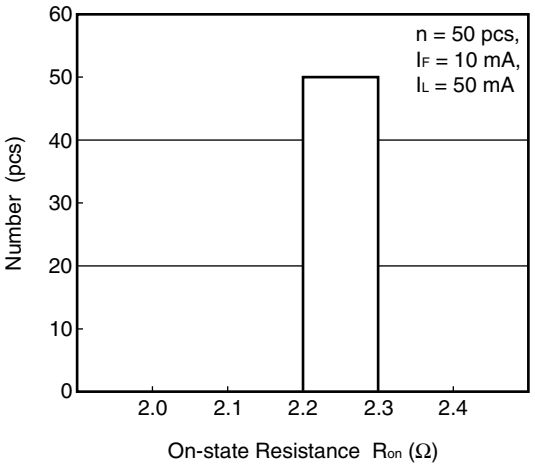


Remark The graphs indicate nominal characteristics.

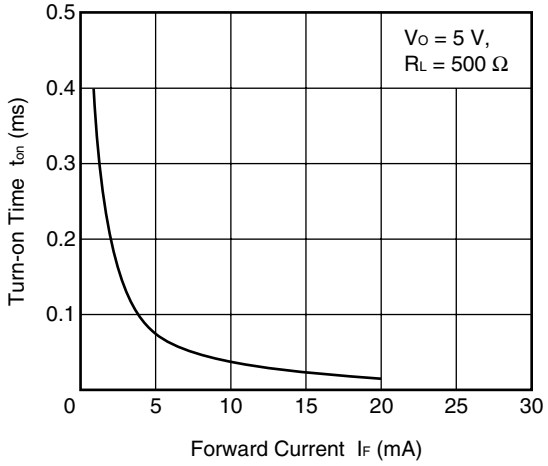
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



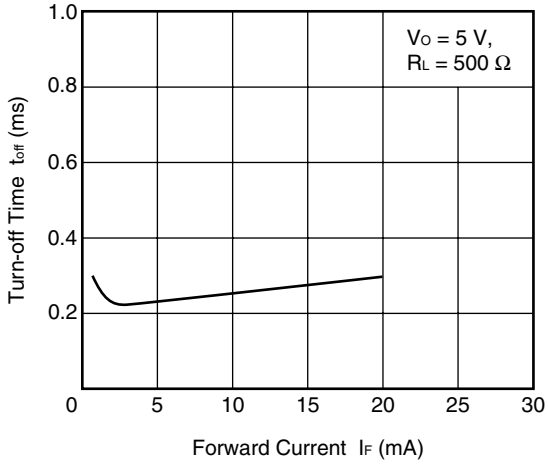
ON-STATE RESISTANCE DISTRIBUTION



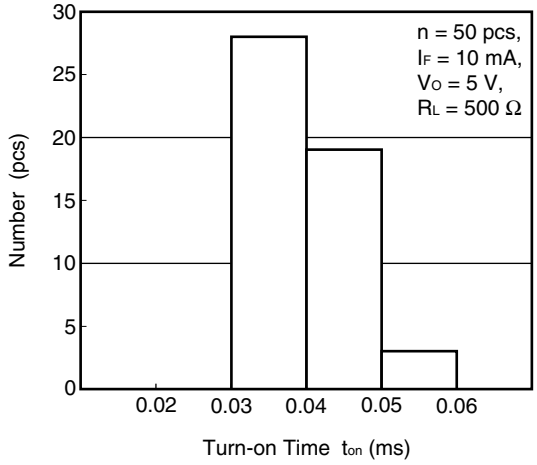
TURN-ON TIME vs. FORWARD CURRENT



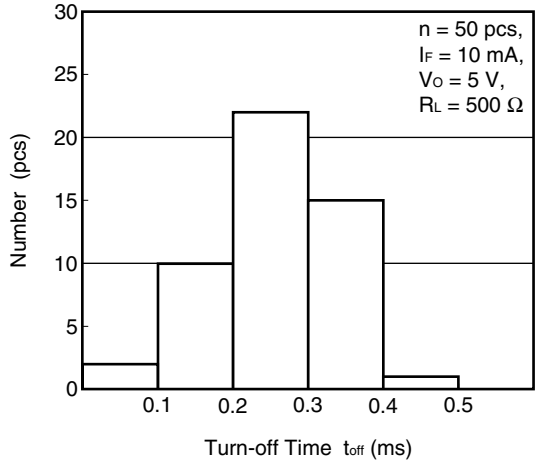
TURN-OFF TIME vs. FORWARD CURRENT



TURN-ON TIME DISTRIBUTION

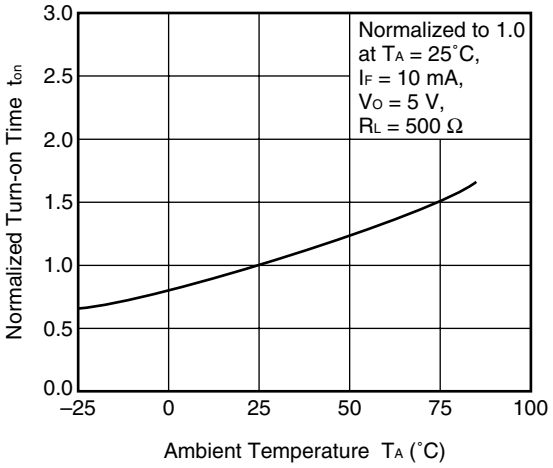


TURN-OFF TIME DISTRIBUTION

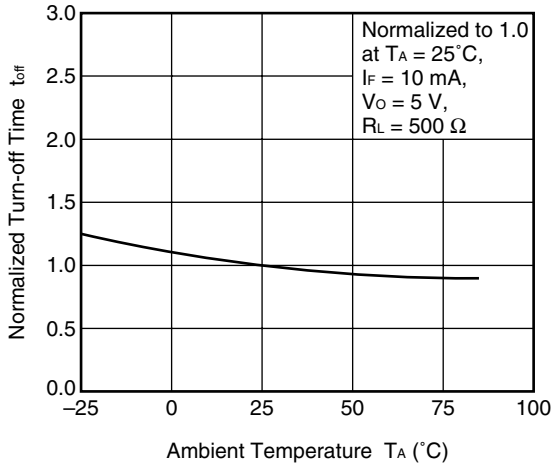


Remark The graphs indicate nominal characteristics.

NORMALIZED TURN-ON TIME vs.
AMBIENT TEMPERATURE



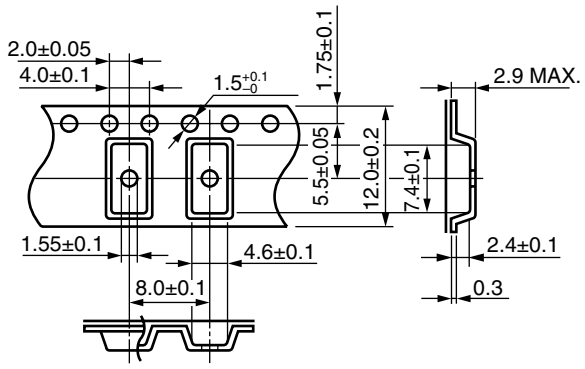
NORMALIZED TURN-OFF TIME vs.
AMBIENT TEMPERATURE



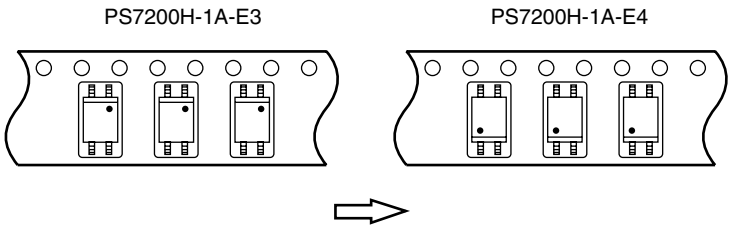
Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (UNIT: mm)

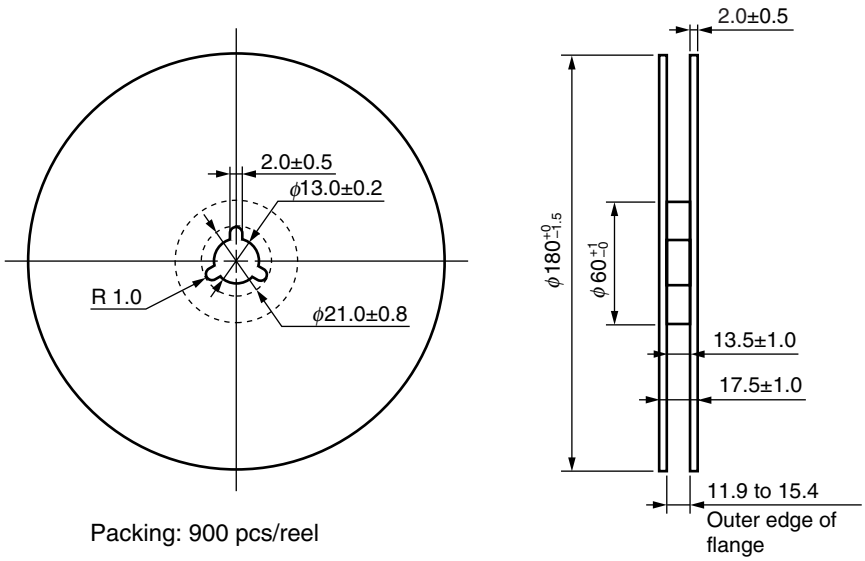
Outline and Dimensions (Tape)



Tape Direction

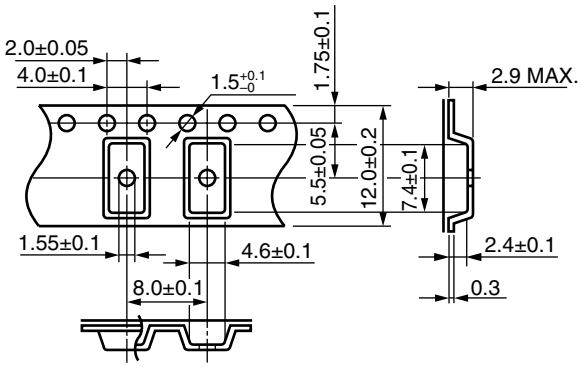


Outline and Dimensions (Reel)

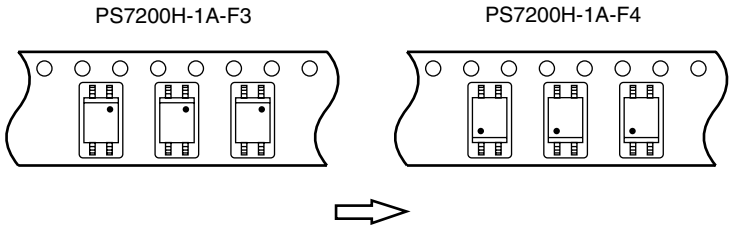


Packing: 900 pcs/reel

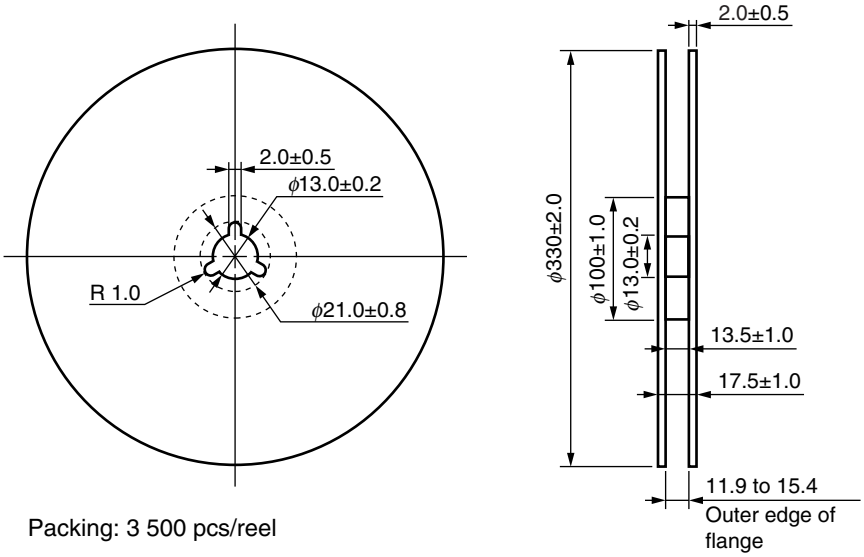
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)



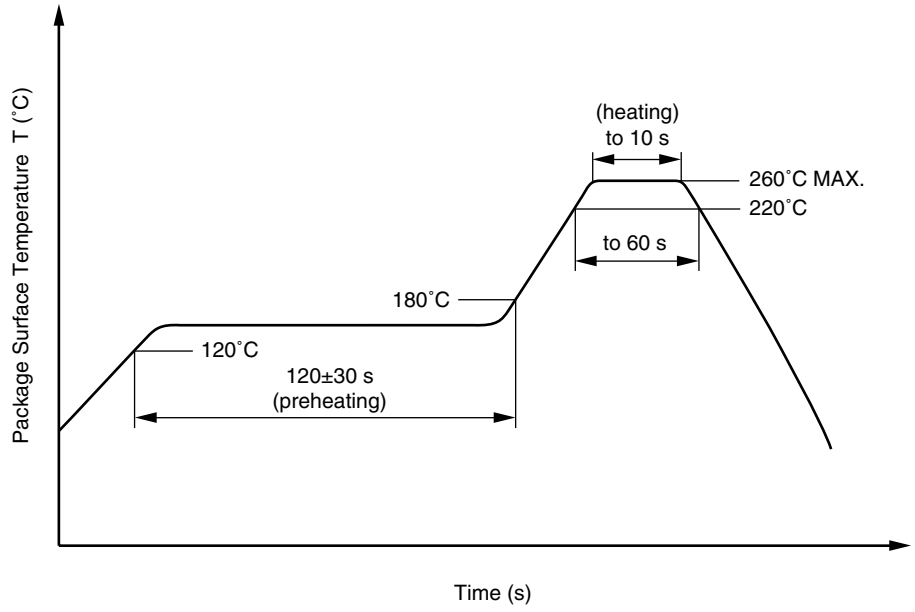
Packing: 3 500 pcs/reel

RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

• Peak reflow temperature	260°C or below (package surface temperature)
• Time of peak reflow temperature	10 seconds or less
• Time of temperature higher than 220°C	60 seconds or less
• Time to preheat temperature from 120 to 180°C	120±30 s
• Number of reflows	Three
• Flux	Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

• Temperature	260°C or below (molten solder temperature)
• Time	10 seconds or less
• Preheating conditions	120°C or below (package surface temperature)
• Number of times	One
• Flux	Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

<R> **(3) Soldering by soldering iron**

• Peak temperature (lead part temperature)	350°C or below
• Time (each pins)	3 seconds or less
• Flux	Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

• Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

<R> **USAGE CAUTIONS**

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

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M8E 02. 11-1

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▶**For further information, please contact**

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